



① Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]
FR4/G10 or equivalent high temp material.

② Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

372 position BGA surface mount land pattern to terminal pins (1.27mm [0.050"] centers, 20x20 array)

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

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	<p>Drawing: Vinayak R</p>	<p>Date: 4/3/08</p>	<p>File: LS-BGA372B-31 Dwg</p>	<p>Modified:</p>